

The XM28C040P is a high density CMOS byte alter-

able nonvolatile memory array constructed on a cofired ceramic substrate using Xicor's 128K x 8 compo-

nents in 32-pad leadless chip carriers. The Substrate is

The module is configured with four separate chip

enable and write enable inputs and 32 separate I/Os.

This, along with the small footprint, provides the end

user with a large degree of flexibility in board layout and

memory configuration. In addition, with the large num-

ber of pins and the growth path being implemented, the

module will be able to grow to 16 megabits.

4 Megabit Puma Module

XM28C040P

512K x 8 Bit

High Density 5 Volt Byte Alterable Nonvolatile Memory Array

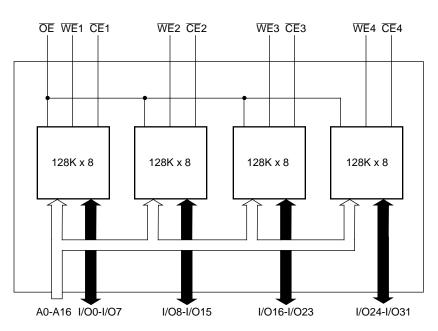
DESCRIPTION

a 66-pin ceramic pin grid array.

FEATURES

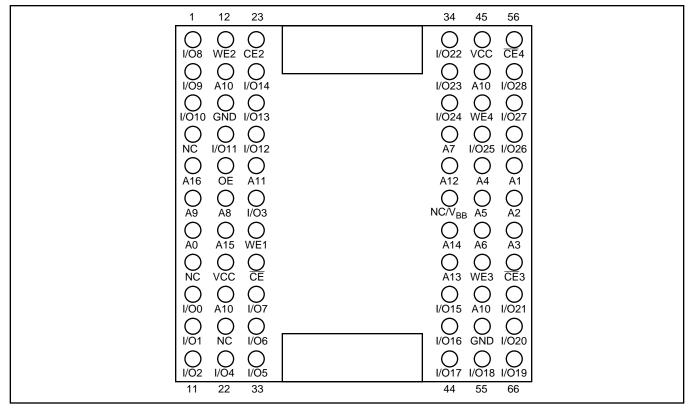
- High Density Memory Module
 - -150ns, 200ns, and 250ns Access Times Available
 - -4 Megabit Memory in 1 square inch.
- Flexible Multiplane Architecture
- —Four Separate Chip Selects
- -32 Separate I/Os
 - User Configurable I/Os—x8, x16, or x32
 - User Configurable Page Size—64 Doublewords, 128 Words, or 256 Bytes
- -Concurrent Read/Write Operations
 - Able to Continue Reading During a Nonvolatile Write Cycle.
- 5 Volt Byte or Page Alterable
 - -No Erase Before Write
- Software Data Protection
 Early End of Write Polling
- DATA Polling
 - -Toggle Bit Polling
- High Reliability
 - -Endurance: 100,000 Cycles
 - -Data Retention: 100 Years

FUNCTIONAL DIAGRAM

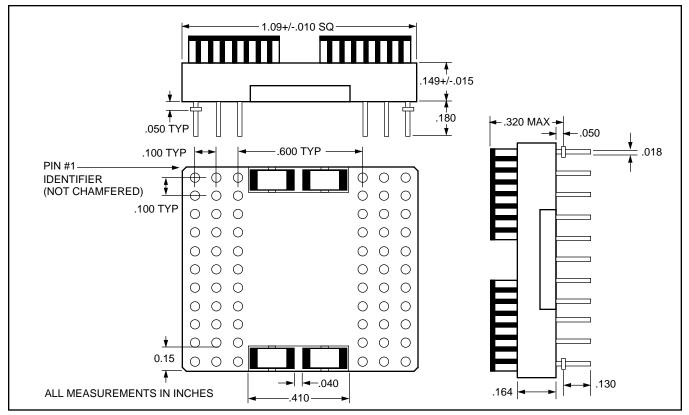


XM28C040P

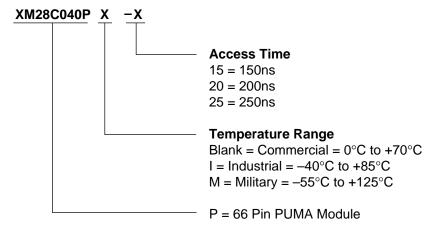
PIN CONFIGURATION



PACKAGE INFORMATION



ORDERING INFORMATION



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U.S. PATENTS

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Xicor's products are not authorized for use in critical components in life support devices or systems

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.